PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT5364057

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
TAKAYUKI MATSUSHITA	02/06/2019
TOMOKI YAMASAKI	02/06/2019

RECEIVING PARTY DATA

Name:	NITTA HAAS INCORPORATED
Street Address:	4-4-26, SAKURAGAWA, NANIWA-KU, OSAKA-SHI,
City:	OSAKA
State/Country:	JAPAN
Postal Code:	556-0022

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15129838

CORRESPONDENCE DATA

Fax Number:	(703)504-9415

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone:	2028351111
Email:	tlim@clarkbrody.com
Correspondent Name:	CLARK & BRODY
Address Line 1:	1700 DIAGONAL ROAD, SUITE 510
Address Line 4:	ALEXANDRIA, VIRGINIA 22314

ATTORNEY DOCKET NUMBER:	12116-0042
NAME OF SUBMITTER:	CHRISTOPHER W. BRODY
SIGNATURE:	/Christopher W. Brody/
DATE SIGNED:	02/07/2019

Total Attachments: 2
source=ass1#page1.tif
source=ass1#page2.tif

Docket No.: ______________________

ASSIGNMENT

This is an Assignment of the following rights, title and interest:

☐ United States of America rights, title and interest in the invention

☐ Foreign rights, title and interest in the invention

☒ International Application No. PCT/JP2015/059924

Date of Filing: March 30, 2015

☐ United States Patent Application Serial No. ______________________

Date of Filing: ______________________

Title of the Invention: POLISHING COMPOSITION AND POLISHING METHOD

Inventors (Assignors): Takayuki MATSUSHITA of c/o NITTA HAAS INCORPORATED, Kyoto Plant, 3-17-1, Kan-nabidai, Kyotanabe-shi, Kyoto 610-0333 Japan

Tomoki YAMASAKI of c/o NITTA HAAS INCORPORATED, Kyoto Plant, 3-17-1, Kan-nabidai, Kyotanabe-shi, Kyoto 610-0333 Japan

Assignee(s): NITTA HAAS INCORPORATED of 4-4-26, Sakuragawa, Naniwa-ku, Osaka-shi, Osaka 556-0022 Japan

Whereas, we, the above-identified Inventors, have invented certain new and useful improvements in the Invention identified above and described in the above-identified patent application(s) and/or patent(s) (hereinafter referred to as "Invention");

And, whereas we desire to assign our above-identified rights, title and interest in the Invention to the above-identified assignee;

Now, this indenture witnesseth, that for good and valuable consideration, the receipt whereof is hereby acknowledged;

We hereby assign, sell and transfer our above-identified rights, title and interest in said Invention, said applications(s) as identified above, including any divisions, continuations, and continuations-in-part thereof, and in and to any and all Letters Patent of the United States, which may be granted or have granted for said Invention, and in and to any and all reissues and reexaminations thereof, and in and to any and all priority rights, Convention rights, and other benefits accruing or to accrue to us with respect to the filing of applications for patents or securing of patents in the United States, unto said Assignee.

And we hereby authorize and request the Commissioner of Patents and Trademarks to issue any United States Letters Patent which may issue for said Invention to said Assignee, as assignee of the whole right, title and interest thereto;

And we further agree to sign and execute all necessary and lawful future documents, including applications, for filing divisions, continuations and continuations-in-part of said application for patent, and/or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid Invention, as the Assignee or its Designee(s) may from time to time require and prepare at its own expense.

松下 隆幸

Signature: Takayuki MATSUSHITA

February 6, 2019

Date

山崎 智基

Signature: Tomoki YAMASAKI

February 6, 2019

Date